Memory



The Memory/Processor Performance Gap



Memory-Processor Performance Gap



The memory hierarchy





The memory hierarchy





Fundamentals of Memory Hierarchy

- Locality
 - Temporal locality
 - The currently required data are likely to need again in the near future
 - Spatial locality
 - There is high probability that the other data nearby will be need soon



Two Processor/Memory Architectures





Memory Access Process



TLB (Translation lookaside buffer): Translate a virtual address to a physical address



Memory management units

- Handles DRAM refresh, bus interface and arbitration
- Takes care of memory sharing among multiple processors
- Translates logic memory addresses from processor to physical memory addresses



Memory Data Organization

- Endianness
 - Big Endian/Little Endian
- Memory data alignment



Endianness

- The order of bytes (sometimes "bit") in memory to represent different data types
- Little/Big Endian
 - Little Endian:
 - put the least-significant byte first (at lower address)
 - e.g. Intel Processor
 - Big Endian:
 - put the most-significant byte first
 - e.g.some PowerPCs, Motorola, MIPS, SPARC



Big/Little Endian Example

• 32bit data 0xFABC0123 at address 0xFF20

	0xFF20	0xFF21	0xFF22	0xFF23
Big Endian	0xFA	0xBC	0x01	0x23
Little Endian	0x23	0x01	0xBC	0xFA

Data Alignment

- Data alignment
 - A datum with multiple bytes need to be allocated to an address that is a multiple of its size
- Examples
 - Obxxxxxxxx byte (8bit) aligned
 - 0bxxxxxxx0 half word (16bit) aligned
 - 0bxxxxxx00 word (32bit) aligned
 - 0bxxxxxx000 double word (64bit) aligned
- Why aligned?
 - Misalignment causes implementation complications and reduces performance



Memory device: basic concepts

- Stores large number of bits
 - *m* x *n*: *m* words of *n* bits each
 - $k = Log_2(m)$ address input signals
 - or $m = 2^k$ words
 - e.g., 4,096 x 8 memory:
 - 32,768 bits
 - 12 address input signals
 - 8 input/output data signals
- Memory access
 - r/w: selects read or write
 - enable: read or write only when asserted
 - multiport: multiple accesses to different locations simultaneously

<u>m × n memory</u>



memory external view





Memory Types

Memory Type	Category	Erasure	Write Mechanism	Volatility
Random-access memory (RAM)	Read-write memory	Electrically, byte-level	Electrically	Volatile
Read-only memory (ROM)	Read-only memory	Not possible	Masks	
Programmable ROM (PROM)				Nonvolatile
Erasable PROM (EPROM)	Read-mostly memory	UV light, chip-level	Electrically	
Electrically Erasable PROM (EEPROM)		Electrically, byte-level		
Flash memory		Electrically, block-level		



ROM: "Read-Only" Memory

- Nonvolatile memory
- Can be read from but not written to, by a processor in an embedded system
- Traditionally written to, "programmed", before inserting to embedded system
- Uses
 - Store software program for general-purpose processor
 - program instructions can be one or more ROM words
 - Store constant data needed by system
 - Implement combinational circuit

External view





Example: 8 x 4 ROM

- Horizontal lines = words
- Vertical lines = data
- Lines connected only at circles
- Decoder sets word 2's line to 1 if address input is 010
- Data lines Q3 and Q1 are set to 1 because there is a "programmed" connection with word 2's line
- Word 2 is not connected with data lines Q_2 and Q_0
- Output is 1010

Internal view





Implementing combinational function

 Any combinational circuit of *n* functions of same *k* variables can be done with 2^k x *n* ROM





Types of ROM

- Written during manufacture
- Programmable (once)
 - PROM
 - Needs special equipment to program
- Read "mostly"
 - Erasable Programmable (EPROM)
 - Erased by UV
 - can program and erase individual words
 - Electrically Erasable (EEPROM)
 - Takes much longer to write than read
 - can program and erase individual words as well
 - Flash memory
 - Large blocks of memory read/write at once, rather than one word at a time
 - Faster erase



RAM

- Random access memory
- Typically volatile memory
 - bits are not held without power supply
- Read and written easily by processor during execution
- Internal structure more complex than ROM
 - a word consists of several memory cells, each storing 1 bit
 - each input and output data line connects to each cell in its column
 - rd/wr connected to every cell
 - when row is enabled by decoder, each cell has logic that stores input data bit when rd/wr indicates write or outputs stored bit when rd/wr indicates read



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Types of RAM

- SRAM: Static RAM
 - Memory cell uses flip-flop to store bit
 - Holds data as long as power supplied
- DRAM: Dynamic RAM
 - Memory cell uses transistor and capacitor to store bit
 - More compact than SRAM
 - "Refresh" required due to capacitor leak
 - Slower to access than SRAM



Device Schematic and Time Diagram





Composing memory

- Memory size needed often differs from size of readily available memories
- When available memory is larger, simply ignore unneeded highorder address bits and higher data lines
- When available memory is smaller, compose several smaller memories into one larger memory
 - Connect side-by-side to increase width of words
 - Connect top to bottom to increase number of words
 - added high-order address line selects smaller memory containing desired word using a decoder
 - Combine techniques to increase number and width of words





enable

outputs

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Summary

- Memory hierarchy
- Memory/processor architecture
- Memory access process
 - Endianness
 - Data alignment
- Memory data organization
- Memory devices
 - Basics
 - ROM/RAM

